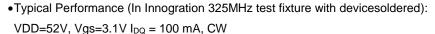
1100W, 50V High Power RF LDMOS FETs

Description

The MQ051K1VP is a 1100-watt, unmatched LDMOS FETs, designed for Aerospace and Air Navigation System applications with frequencies from HF to 0.6GHz.

 \bullet Typical Performance (In Innogration 325MHz test fixture with device soldered) VDD=52V, Vgs=3.1V I_{DQ} = 100 mA, Pulse CW, Pulse Width=100 us, Duty cycle=10% .

Pin(dBm)	Pout(W)	Power Gain (dB)	lds(A)	Eff(%)
37	970	22.8	2.79	69.1
38	1023	22.1	2.93	69.3
39	1071	21.3	3.03	69.9
40	1122	20.5	3.14	70.5



Pin(dBm)	Pout(W)	Power Gain (dB)	lds(A)	Eff(%)
38	933	21.7	26.2	68.5
39	1000	21	27.4	70.2
40	1023	20.1	28	70.3

• Capable of Handling >20:1 VSWR at all phase angle, @ 52Vdc, 325 MHz,1000Watts Pulse CW Output Power

Features

- High Efficiency and Linear Gain Operations
- Integrated ESD Protection
- Internally Matched for Ease of Use
- Large Positive and Negative Gate/Source Voltage Range for Improved Class C Operation
- · Excellent thermal stability, low HCI drift
- Compliant to Restriction of Hazardous Substances (RoHS) Directive 2002/95/EC

Table 1. Maximum Ratings

8			
Rating	Symbol	Value	Unit
DrainSource Voltage	V _{DSS}	125	Vdc
GateSource Voltage	V _{GS}	-10 to +10	Vdc
Operating Voltage	V _{DD}	+55	Vdc
Storage Temperature Range	Tstg	-65 to +150	°C
Case Operating Temperature	T _c	+150	°C
Operating Junction Temperature	Τ _J	+225	°C

Table 2. Thermal Characteristics

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Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case, Case Temperature	Do 10	TDD	0000
80°C, 1000W Pulse CW, 50 Vdc, IDQ = 100 mA	Rejc	TBD	°C/W

Table 3. ESD Protection Characteristics

Test Methodology	Class
Human Body Model (per JESD22A114)	Class 2

Table 4. Electrical Characteristics (TA = 25 °C unless otherwise noted)

Characteristic	Symbol	Min	Тур	Max	Unit	
DC Characteristics						
Drain-Source Voltage	M		400		V	
V_{GS} =0, I_{DS} =1.0Ma	$V_{(BR)DSS}$		122		V	
Zero Gate Voltage Drain Leakage Current				4	۸	
$(V_{DS} = 50V, V_{GS} = 0 V)$	I _{DSS}			1	μΑ	
Gate—Source Leakage Current				4	۸	
$(V_{GS} = 10 \text{ V}, V_{DS} = 0 \text{ V})$	I _{GSS}			1	μΑ	
Gate Threshold Voltage	V _{GS} (th)		2.53		V	
$(V_{DS} = 50V, I_D = 600 \mu A)$					V	
Gate Quiescent Voltage	$V_{\text{GS}(Q)}$		3.1		V	
$(V_{DD} = 50 \text{ V}, I_D = 400 \text{ mA}, \text{Measured in Functional Test})$					V	
Drain source on state resistance	Rds(on)		94.6		mΩ	
(VDS = 0.1V, VGS = 10 V) Each section side of device measured	Rus(on)		94.0		11122	
Common Source Input Capacitance	C _{ISS}		327		pF	
$(V_{GS} = 0V, V_{DS} = 50 \text{ V}, f = 1 \text{ MHz})$ Each section side of device measured						
Common Source Output Capacitance	Coss		97.3		pF	
($V_{GS} = 0V$, $V_{DS} = 50$ V, f = 1 MHz) Each section side of device measured						
Common Source Feedback Capacitance	C _{RSS}		1.95		pF	
$(V_{GS} = 0V, V_{DS} = 50 \text{ V}, f = 1 \text{ MHz})$ Each section side of device measured						

Figure 1: CW gain and efficiency as a Function of Output Power

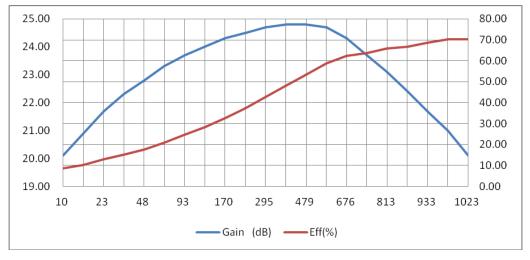
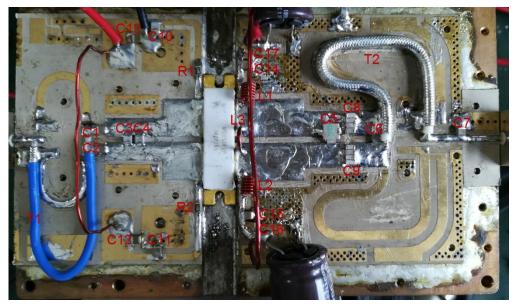


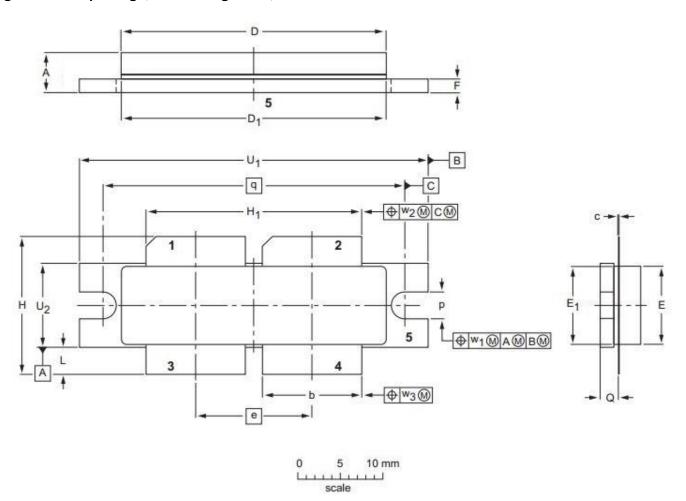
Figure 2: 325MHz test fixture picture



	ВОМ	
C1,C2,C10,C11,C14,C15	300PF	ATC800B
C3	39PF	ATC800B
C4	33PF	ATC800B
C5	36PF	CDE
C6	2.7PF	ATC800B
C7	2.2PF	ATC800B
C8,C9	68PF x4	ATC800B
C12,C13,C16,C17	1UF	
R1,R2	25 Ω	
L1, L2	6turns	Diameter=3.5mm
L3	1turns	Diameter=7.5mm
T1	25 Ω 100mm	
T2	25 Ω 112mm	

Package Outline

Flanged ceramic package; 2 mounting holes; 4 leads (1, 2—DRAIN, 3, 4—GATE, 5—SOURCE)



UNIT	Α	b	С	D	D ₁	е	E	E ₁	F	Н	H ₁	L	р	Q	q	U ₁	U_2	W_1	W_2	W_2
mm	4.7	11.81	0.18	31.55	31.52	13.72	9.50	9.53	1.75	17.12	25.53	3.48	3.30	2.26	35.56	41.28	10.29	0.25	0.51	0.25
	4.2	11.56	0.10	30.94	30.96	13.72	9.30	9.27	1.50	16.10	25.27	2.97	3.05	2.01	33.30	41.02	10.03	0.23	0.51	0.23
inahaa	0.185	0.465	0.007	1.242	1.241	0.540	0.374	0.375	0.069	0.674	1.005	0.137	0.130	0.089	4 400	1.625	0.405	0.04	0.00	0.04
inches	0.165	0.455	0.004	1.218	1.219	0.540	0.366	0.365	0.059	0.634	0.995	0.117	0.120	0.079	1.400	1.615	0.395	0.01	0.02	0.01

OUTLINE		REFERENCE		EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA	PROJECTION	IOOOL DATE
PKG-D4E					03/12/2013

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Revision history

Table 6. Document revision history

Date	Revision	Datasheet Status
2017/07/31	Rev 1.0	Preliminary Datasheet

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